Product / Process Change Notification



N° 2020-160-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity extension with the introduction of an additional assembly and final test location at Great Team Backend Foundry, Inc., China for dedicated OptiMOS3 products in WDSON package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **10 February 2021**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Wolfgang Eder Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider Registered Office: Neubiberg Commercial Register: München HRB 126492

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Products affected: Please refer to attached affected product list 1_cip20160_a

Detailed Change Information:

Subject:	Capacity extension with the introduction of an additional assembly and final test location at Great Team Backend Foundry, Inc., China for dedicated OptiMOS3 products in WDSON package				
Reason:	Expansion of assembly and final test to assure continuity of supply and enable flexible manufacturing. Harmonization of bill of materials (BoM) across the WDSON assembly location.				
Description:	<u>Old</u>	New			
Assembly and Final Test location:	 Infineon Technologies (Malaysia) Sdn. Bhd., Malaysia 	 Infineon Technologies (Malaysia) Sdn. Bhd., Malaysia and Great Team Backend Foundry, Inc., China 			
Marking:	• 2 digit lotcode	 2 digit lotcode and 4 digit lotcode 12 3 4 12 3 4 Lotcobe Lotcobe Lotcobe 			
Package Nomenclature	 MG-WDSON-2 	 MG-WDSON-2 and MG-WDSON-5 			
Bill of Materials (BoM):	 Leadframe brightness 0.8-1.4 G.A.M 	 Leadframe brightness 0.8-1.4 G.A.M Reduced leadframe brightness 0.6-0.7 G.A.M 			

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Product Identification:

<u>External traceability</u>: assured via new sales product number, orderable part number (OPN) & country of assembly

Country of assembly:

- Malaysia = "Infineon Technologies (Malaysia) Sdn. Bhd." production
- China = "Great Team Backend Foundry, Inc." production



► Impact of Change: NO change of electrical and thermal parameters as proven via product qualification and characterization.

NO change in existing datasheet parameters

NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification.

NO change in the package outline dimensions.

► Attachments:

Affected product list1_ cip20160_aQualification Report2_cip20160_aCustomer Information Package3_cip20160_a (available by 31 Jan 2021)

► Time Schedule:

Final qualification report:	available
 First samples available: 	on request
Intended start of delivery:	30 March 2021 (depending on PCN acceptance)

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales name	SP number	OPN	Package
BSB044N08NN3 G	SP000604542	BSB044N08NN3GXUMA1	MG-WDSON-2
BSB056N10NN3 G	SP000604540	BSB056N10NN3GXUMA1	MG-WDSON-2
BSB104N08NP3 G	SP001164330	BSB104N08NP3GXUSA1	MG-WDSON-2
BSB165N15NZ3 G	SP000617000	BSB165N15NZ3GXUMA1	MG-WDSON-2
BSB280N15NZ3 G	SP000604534	BSB280N15NZ3GXUMA1	MG-WDSON-2